
PRODUCT RELIABILITY REPORT

Product: JW1221

	Name	Position
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1. Device Information

Product:	JW1221
Lot# or DateCode:	297C
Package:	SOT23-6
Report Date:	2018/3/3

2. Summary of Test Results

Test Items	Test condition	S.S.	Acc/Re	Fail/Pass	Test Result	Remark
High Temperature Operating Life	JESD22-A108, @+125°C for 1000 Hours or equivalent	77	0/1	0/77	PASS	
ESD: Human Body Model (HBM)	MIL-STD-883H Method 3015.8	21	0/1	0/18	PASS	>2KV
Latch-up	EIA/JESD78	9	0/1	0/9	PASS	200mA or >1.5Vccm ax or ABS
Preconditioning of Nonhermetic Surface Mount Devices Prior to Reliability Testing (Precondition L1)	Bake: 125°C,24h Soak: 85°C, 85%RH, 168h Reflow: 260°C, 3times	330	0/1	0/330	PASS	MSL=1
Temperature Cycling (TCT)	JESD22-A104 -65°C-150°C, Dwell=15min,500/ 1000Cycles	77	0/1	0/77	PASS	

Accelerated Moisture Resistance-Unbiased Autoclave (PCT)	JESD22-A102 121°C 100%RH, 205 kPa,168h	77	0/1	0/77	PASS	
Accelerated Moisture Resistance-Unbiased HAST (uHAST)	JESD22-A118 130°C, 85%RH, 96h	77	0/1	0/77	PASS	
High Temperature Storage Life (HTSL)	JESD22-A103 Ta=150°C,500/1000h	77	0/1	0/77	PASS	

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Appendix: Description of Reliability Test and Failure Rate Calculation

High Temperature Operating Life Test

Purpose: This test is a worst-case life test that checks the integrity of the product. The high temperature testing is use for acceleration of any potential failures over time. The calculation for failure rate (FIT) using the operating ambient temperature is done using the arrhenius equation.

Condition: 125°C @ Vccmax

Pass Criteria: All units must pass the min/max limits of the datasheet.

ESD Test

Purpose: The purpose of the ESD test is to guarantee that the device can withstand electrostatic voltages during handling.

Condition: Human Body Model, Machine Model and Charged Device Model.

Pass Criteria: ESD Testing on every pin. The device must be fully functional after testing and pass the min/max limits in the datasheet.

IC Latch-Up Test

Purpose: The purpose of this specification is to establish a method for determining IC latch-up characteristics and to define latch-up failure criteria. Latch-up characteristics are extremely important in determining product reliability and minimizing No Trouble Found (NTF) and Electrical Overstress (EOS) failures due to latch-up.

Condition: Voltage and current injection

Pass criteria: All pins with the exception of “no connect” pins and timing related pins, shall be latch-up tested. The device must be fully functional after testing and pass the min/max limits in the datasheet.

Preconditioning of Nonhermetic Surface Mount Devices Prior to Reliability Testing

Purpose: The purpose of this standard is to identify the classification level of nonhermetic solid state surface mount devices (SMDs) that are sensitive to moisture-induced stress so that they can be properly packaged, stored, and handled to avoid damage during assembly solder reflow attachment and/or repair operations.

Condition: Bake + moisture sock + 3X reflow at 260°C

Pass criteria: All units must pass the min/max limits of the datasheet

Accelerated Moisture Resistance- Unbiased Autoclave

Purpose: To check the performance of the device in humid environments. This test checks the integrity of the passivation, poor metal to plastic seal and contamination level during assembly and material compatibility.

Condition: 121°C/15psig/100% RH (no bias)

Pass Criteria: All units must pass min/max limits of the datasheet.

Temperature Cycle Test

Purpose: This test is used to evaluate the die attach integrity and bond integrity. This is similar to the Thermal Shock test, but can generate different failure modes due to the longer dwell time and gradual temperature change.

Condition: -65°C to 150°C

Pass Criteria: All units must pass min/max limits of the datasheet.

Accelerated Moisture Resistance-Unbiased HAST

Purpose: To evaluate the reliability of non-hermetic packaged solid-state devices in humid environment. This test is used to identify failure mechanisms internal to the package and is destructive.

Condition: 130°C, 85%RH, 96h

Pass Criteria: All units must pass min/max limits of the datasheet.

High Temperature Storage Life

Purpose: This test is basically used to determine if the effects of diffusion, oxidation, intermetallic growth, and chemical degradation of packaging components will affect product life.

Condition: Ta=150°C+ Preconditioning if Required, T=1000h

Pass Criteria: All units must pass min/max limits of the datasheet.

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